RENESAS

HSM88AS

Silicon Schottky Barrier Diode for Balanced Mixer

REJ03G0135-0600Z (Previous: ADE-208-046E) Rev.6.00 Nov.06.2003

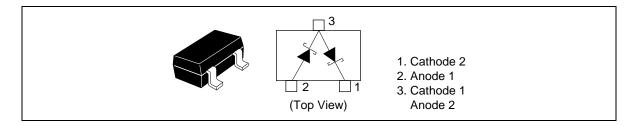
Features

- Proof against high voltage.
- MPAK package is suitable for high density surface mounting and high speed assembly.

Ordering Information

Type No.	Laser Mark	Package Code	
HSM88AS	C1	МРАК	

Pin Arrangement





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Absolute Maximum Ratings

(Ta = 25°C)

Item	Symbol	Value	Unit	
Reverse voltage	V _R	10	V	
Average rectified current	l ₀ * ¹	15	mA	
Junction temperature	Tj	125	°C	
Storage temperature	Tstg	-55 to +125	°C	

Note: 1. Per one device

Electrical Characteristics *¹

(Ta = 25°C)

Item	Symbol	Min	Тур	Max	Unit	Test Condition
Forward voltage	V_{F1}	0.35		0.42	V	$I_F = 1 \text{ mA}$
	V _{F2}	0.50		0.58	-	I _F = 10 mA
Reverse current	I _{R1}	_	_	0.2	μΑ	$V_R = 2 V$
	I _{R2}	_	_	10	-	V _R = 10 V
Capacitance	С			0.85	pF	$V_R = 0 V, f = 1 MHz$
Capacitance deviation	ΔC	_	_	0.10	pF	$V_R = 0 V, f = 1 MHz$
Forward voltage deviation	ΔV_{F}	_		10	mV	I _F = 10 mA
ESD-Capability *2		30	_	—	V	C = 200 pF, R = 0 Ω , Both forward and reverse direction 1 pulse.

Notes: 1. Per one device

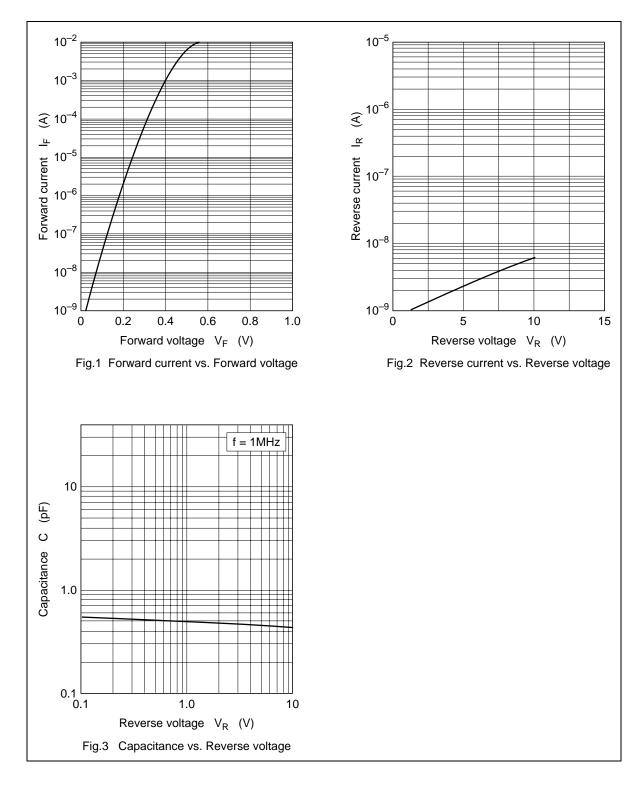
2. Failure criterion ; $I_R \geq 0.4~\mu A$ at V_R = 2 V

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Main Characteristics

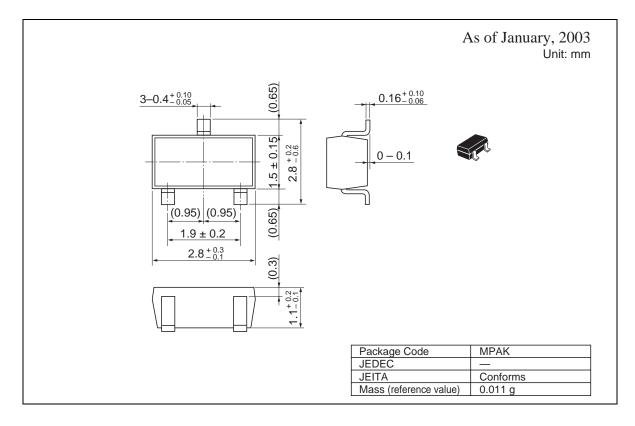


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Package Dimensions



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